

ABSTRACT

There is provided a method for manufacturing a printed wiring board, including the following steps. Forming a resin layer on a printed wiring board with circuit patterns formed thereon wherein the resin layer is formed by superposing a semi-cured resin sheet, in which patterns complementary to the circuit patterns are included on a surface of the resin sheet facing the circuit patterns. Pressing and forcing the resin layer into spaces between the circuit patterns and curing the resin layer. And then polishing the cured resin covering said circuit patterns, thereby exposing said circuit patterns.